

**METHOD FOR PRODUCING DUAL DAMASCENE INTERCONNECTIONS  
AND STRUCTURE PRODUCED THEREBY**

**ABSTRACT**

A method (and structure) of forming an interconnect on a semiconductor  
5 substrate, includes forming a relatively narrow first structure in a dielectric formed on a  
semiconductor substrate, forming a relatively wider second structure in the dielectric  
formed on the semiconductor substrate, forming a liner in the first and second structures  
such that the first structure is substantially filled and the second structure is substantially  
unfilled, and forming a metallization over the liner to completely fill the second structure.

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